

HAT2024R-VB Datasheet **Dual N-Channel 30-V (D-S) MOSFET**

PRODUCT SUMMARY					
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A)	Q _g (Typ.)		
30	$0.022 \text{ at V}_{GS} = 10 \text{ V}$	6.8	15 nC		
30	0.026 at V _{GS} = 4.5 V	6.0	10110		

 D_1

 D_2

SO-8

Top View

FEATURES

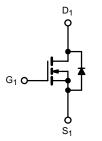
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- 100 % UIS Tested
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC

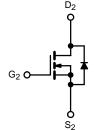


COMPLIANT HALOGEN FREE

APPLICATIONS

- Set Top Box
- Low Current DC/DC





N-Channel MOSFET

N-Channel MOSFET

ABSOLUTE MAXIMUM RATINGS T _A = 25 °C, unless otherwise noted					
Parameter	Symbol	Limit	Unit		
Drain-Source Voltage	V _{DS}	30	V		
Gate-Source Voltage		V_{GS}	± 20	V	
	T _C = 25 °C		6.8 ^a		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		5.6		
Continuous Brain Current (1) = 100 °C)	T _A = 25 °C	l _D	6.2 ^{b, c}		
	T _A = 70 °C		5.2 ^{b, c}	Α	
Pulsed Drain Current	I _{DM}	30			
Continuous Course Brain Binds Courset	T _C = 25 °C	1_	2.25		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	1.48 ^{b, c}		
Single Pulse Avalanche Current	L = 0.1 mH	I _{AS}	5		
Single Pulse Avalanche Energy	L=0.1 IIII	E _{AS}	1.25	mJ	
	T _C = 25 °C		2.7		
Maximum Dawar Dissination	T _C = 70 °C		1.77	W	
Maximum Power Dissipation	T _A = 25 °C	P _D	1.78 ^{b, c}	VV	
	T _A = 70 °C		1.14 ^{b, c}		
Operating Junction and Storage Temperatur	$T_{\rm J}, T_{\rm sto}$	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS						
Parameter		Symbol	Typical	Maximum	Unit	
Maximum Junction-to-Ambient ^{a, c, d}	t ≤ 10 s	R _{thJA}	58	70	°C/W	
Maximum Junction-to-Foot (Drain)	Steady State	$R_{th,IF}$	38	45		

Notes:

- a. Package limited, T_C = 25 °C.
 b. Surface Mounted on 1" x 1" FR4 board.
- d. Maximum under Steady State conditions is 110 °C/W.

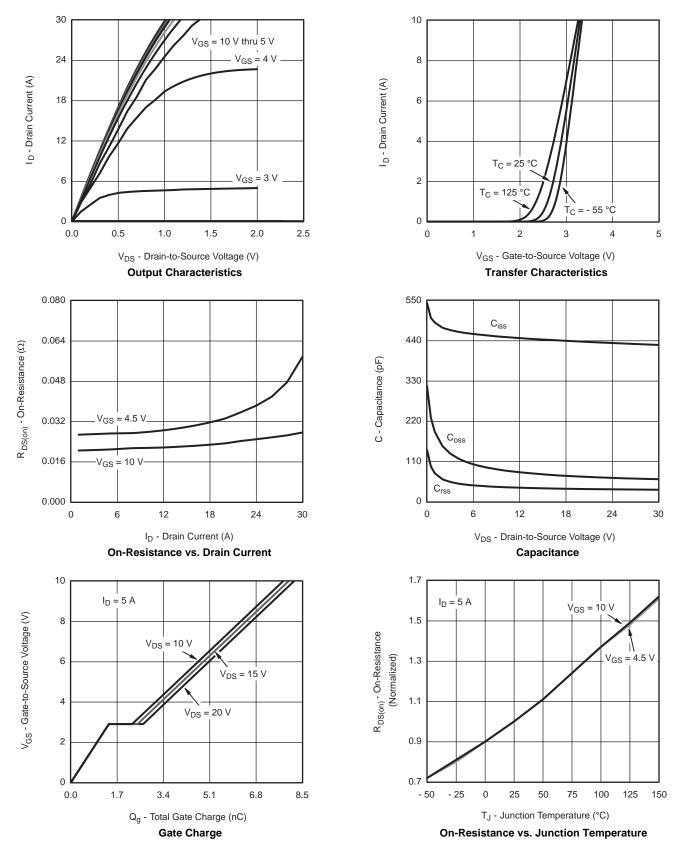


Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static						•
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	/T.		32		
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	$I_D = 250 \mu A$		- 5.0		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_{D} = 250 \mu A$	1.0		2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA
Zara Oata Valla va Daria Oamaal	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	
Zero Gate Voltage Drain Current		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 55 °C			10	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	10			Α
	5	$V_{GS} = 10 \text{ V}, I_D = 5 \text{ A}$		0.022		Ω
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 4 \text{ A}$		0.026		
Forward Transconductance ^a	g _{fs}	$V_{DS} = 10 \text{ V}, I_D = 5 \text{ A}$		16		S
Dynamic ^b	<u> </u>		1		l	l
Input Capacitance	C _{iss}			586		pF
Output Capacitance	C _{oss}	$V_{DS} = 15 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		117		
Reverse Transfer Capacitance	C _{rss}			55		
Total Cata Chausa	Q _g	$V_{DS} = 15 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 5 \text{ A}$		15		nC
Total Gate Charge				3.7	5.6	
Gate-Source Charge	Q_{gs}	$V_{DS} = 15 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 5 \text{ A}$		1.4		
Gate-Drain Charge	Q_{gd}			1.05		
Gate Resistance	R _g	f = 1 MHz	0.8	4.3	8.6	Ω
Turn-On Delay Time	t _{d(on)}			12	24	
Rise Time	t _r	V_{DD} = 15 V, R_L = 3 Ω		55	100	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 5$ A, V_{GEN} = 4.5 V, R_g = 1 Ω		11	22	
Fall Time	t _f			8	16	
Turn-On Delay Time	t _{d(on)}			4	8	ns
Rise Time	t _r	V_{DD} = 15 V, R_L = 3 Ω		9	18	- - -
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 5$ A, V_{GEN} = 10 V, R_g = 1 Ω		10	20	
Fall Time	t _f			6	12	
Drain-Source Body Diode Characteristic	s					
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			2.25	Λ
Pulse Diode Forward Current	I _{SM}				24	A
Body Diode Voltage	V_{SD}	I _S = 2 A, V _{GS} = 0 V		0.8	1.2	V
Body Diode Reverse Recovery Time	t _{rr}			11	20	ns
Body Diode Reverse Recovery Charge	Q _{rr}			4	8	nC
Reverse Recovery Fall Time	ta	$I_F = 5 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		7		
Reverse Recovery Rise Time	t _b	7		4		ns

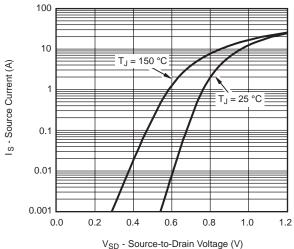
- a. Pulse test; pulse width \leq 300 µs, duty cycle \leq 2 % b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

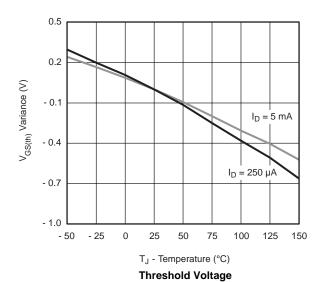




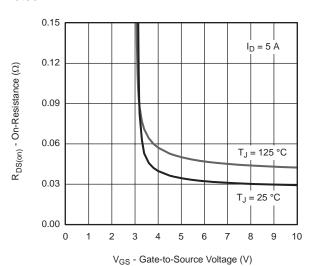




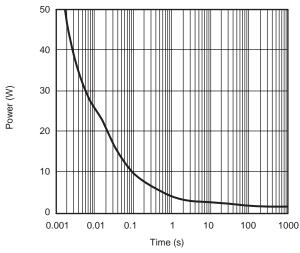
Source-Drain Diode Forward Voltage



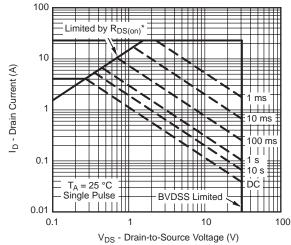
V_{SD} - Source-to-Drain Voltage (V)



On-Resistance vs. Gate-to-Source Voltage



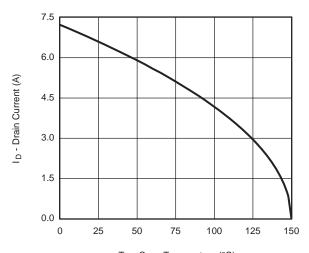
Single Pulse Power



* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

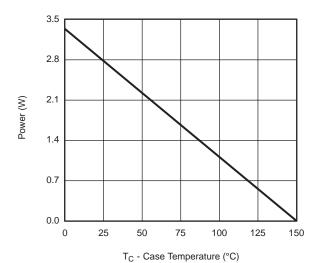
Safe Operating Area, Junction-to-Ambient



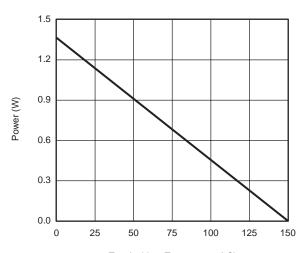


T_C - Case Temperature (°C)

Current Derating*



Power, Junction-to-Foot



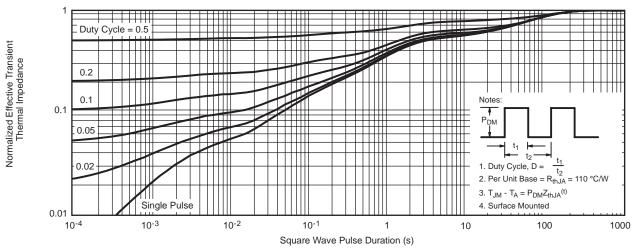
T_A - Ambient Temperature (°C)

Power, Junction-to-Ambient

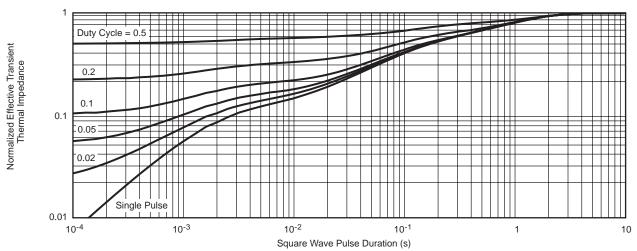
服务热线:400-655-8788 5

^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.





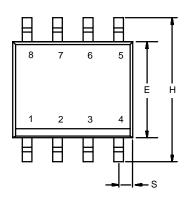
Normalized Thermal Transient Impedance, Junction-to-Ambient

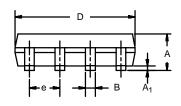


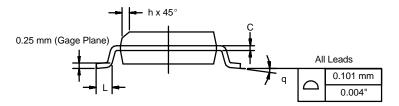
Normalized Thermal Transient Impedance, Junction-to-Foot



SOIC (NARROW): 8-LEADJEDEC Part Number: MS-012







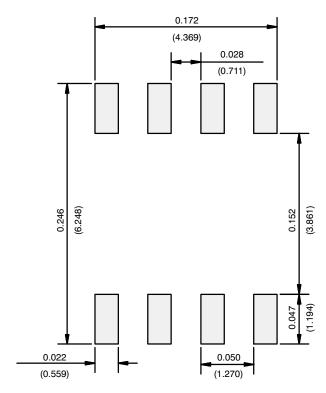
	MILLIMETERS		INC	HES	
DIM	Min	Max	Min	Max	
А	1.35	1.75	0.053	0.069	
A ₁	0.10	0.20	0.004	0.008	
В	0.35	0.51	0.014	0.020	
С	0.19	0.25	0.0075	0.010	
D	4.80	5.00	0.189	0.196	
Е	3.80	4.00	0.150	0.157	
е	1.27 BSC		0.050 BSC		
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.020	
L	0.50	0.93	0.020	0.037	
q	0°	8°	0°	8°	
S	0.44	0.64	0.018	0.026	
FCN: C-06527-Rev I 11-Sep-06					

ECN: C-06527-Rev. I, 11-Sep-06

DWG: 5498



RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)



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